



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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# wakefield-vette

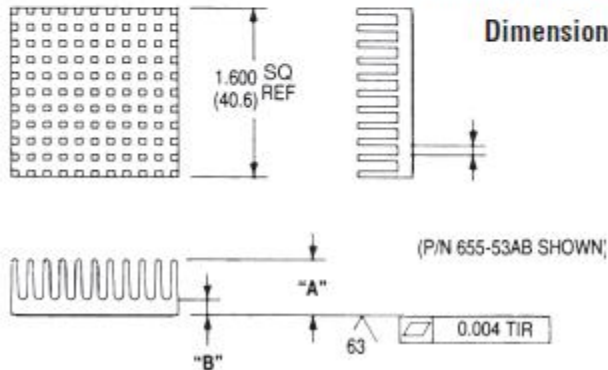
## 655 SERIES

Omnidirectional Pin Fin Heat Sink for BGAs and PowerPC™

Standard P/N	Base Dimensions in. (mm)	Dimension "A" in. (mm)	Dimension "B" in. (mm)	Typical Applications	Heat Sink Finish	Weight lbs. (grams)
655-26AB	1.600 (40.6) sq	0.260 (6.6)	0.125 (3.2)	40mm BGA	Black Anodized	0.038 (17.01)
655-53AB	1.600 (40.6) sq	0.525 (13.3)	0.145 (3.7)	40mm BGA	Black Anodized	0.050 (22.68)

Notes: 1. Optional factory preapplied pressure-sensitive adhesive. See Page 3

## MECHANICAL DIMENSIONS



## NATURAL AND FORCED CONVECTION CHARACTERISTICS

